Join Amkor at IMAPS Device Packaging Conference 2016

Amkor Technology invites you to join us at the IMAPS DPC being held at the WekoPa Resort and Casino, March 15-17 in Fountain Hills, Arizona.

IMAPS DPC is an international event organized by the International Microelectronics Assembly and Packaging Society (IMAPS). The conference is a major forum for the exchange of knowledge and provides numerous technical, social and networking opportunities for meeting leading experts in these fields.

Amkor staff will be presenting or contributing to the following papers:

**Tues. March 15th - Interposers, 3D IC & Packaging Track**
2:00 PM - 2:30 PM - "System Level IC Packaging - Integration of Key Technologies: TSVs, Interposers, and Advanced IC Packaging", Mike Kelly, Sr Director, Adv Package & Technology Integration, Amkor Technology (Dave Hiner, Marnie Mattei, Rick Reed, Paul Silvestri, Ron Huemoeller, Amkor Technology)

2:30 PM - 3:00 PM - "Impact of Top Die Thickness on Cu Pillar Fatigue in Exposed Die 3D Packages", Rahul Agarwal, Globalfoundries (Sukesh Kannan - GF, Shan Gao - GF; Rick Reed, Yong Song - Amkor Technology, JS Paek - Amkor Technology Korea)

**Tues. March 15th - Evening Panel Discussion**
5:00 PM - 6:30 PM - "SiP: New Drivers and the Supply Chain", Robert Lanzone, Sr. VP/AWL&PD, Amkor Technology

**Wed. March 16th - SiP Track**
1:30 PM - 2:00 PM - "Si Photonics Deployment Using Cu Pillar Interconnect and Chip On Wafer Platform", Miguel Jimarez, VP, Adv Package & Technology Integration, Amkor Technology (DongHee Kang, SangYun Ma, Amkor Technology Korea; Rocky Leblanc, Michael Mack, Chang Sohn, Gianlorenzo Masini, Luxtera)

**Thurs. March 17th - SiP Track**
10:15 AM -10:45 AM - "An Innovative Package EMC Solution Using a Highly Cost-Effective Sputtered Conformal Shield", Nozad Karim, VP, Electrical Engineering, Amkor Technology (Rong Zhou, Amkor Technology; Jun Fan, Missouri University of Science and Technology)
In addition, Amkor's Curtis Zwenger, Sr Director, Adv Package & Technology Integration, Nozad Karim, VP, Electrical Engineering and Russell Shumway, Director, Automotive MEMS are session chairs for this event.

Amkor is pleased to be a sponsor of this IMAPS event and will be exhibiting at booth #38 with our technical staff on hand to answer any questions or provide more detail.

For additional information and to register, please visit: http://www.imaps.org/devicepackaging/

Join Us For These Upcoming Events

Mark your calendars and join Amkor at the following events.

03/15/16 | SEMICON China 2016
05/11/16 | 14th Annual MEPTEC MEMS Technology Symposium
05/17/16 | TSMC China Technology Symposium
05/26/16 | TSMC Taiwan Technology Symposium
05/31/16 | ECTC - IEEE/CMPT 65th Electronics Components and Technology Conference

If you have any questions or comments, please contact us at sales@amkor.com.